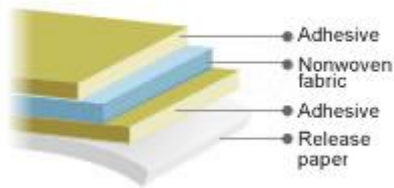


Polyester resin base hotmelt adhesive tape D3615T

Features

- Tack-free characteristics at room temperature allows spinning and direct-punching process without release liner, it effects good workability, and availability for various design feature.
- Well balanced adhesive performance effects excellent bonding strength for various kinds of substrate from plastics to metals from low temperature range.
- Excellent drop impact resistance allows it to be used for narrow bonding area.
- Non-woven fabric carrier eases punching process and supports dimension stability.

Structure



Products Name	D3615T
Main component	Polyester
Carrier	Nonwoven fabric
Color	Translucent white
Adhesive thickness (μm)	about 150
Release paper thickness (μm)	about 60
Bonding strength (N/4cm ²) ※	2207
St'd size (width & length)	460mm × 50m

※ Shear strength (Bonding at 150℃)

Suitable use

- It is suitable for the bonding usage of plastic such as nameplates and front panels of electricity and an electronic equipment (ABS, PS, and acrylic fiber, etc.) and metallic (aluminum and stainless steel plate, etc.) materials.
- It is suitable for the bonding usage of plastic and metallic material such as the car exterior parts.

Technical data

1. Bonding strength under different temperatures (Shear strength)

<Test piece condition>

Substrate① : SUS(0.5 × 25 × 100mm)

Substrate② : PC・ABS(2.0 × 25 × 100mm)

Bonding area : 20mm × 20mm

Bonding condition :

Pressure : 0.5MPa(5kgf/cm²)

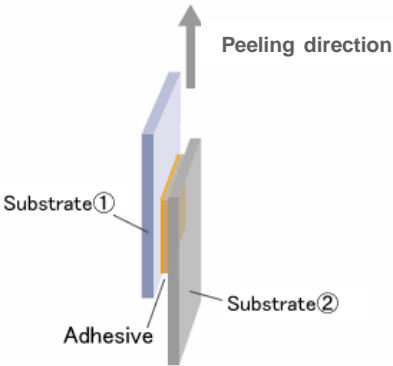
Temperature : 100 to 200℃

Set time : 3 sec

Measuring condition : 23℃±5℃ 60%±20% RH

Peel speed : 20mm/min

[Left at RT for one day before measurement]



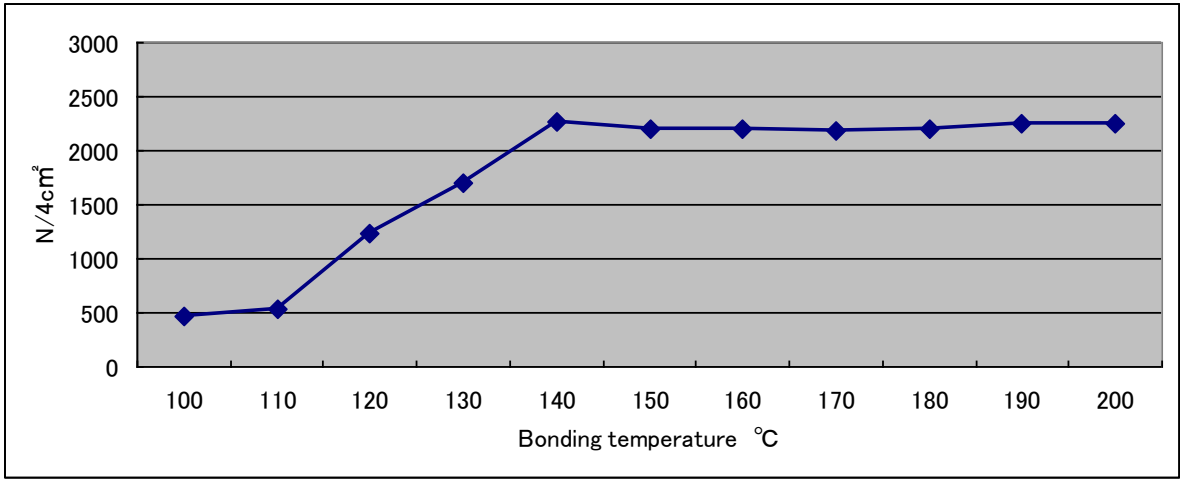
<Shear strength test >

<Results>

	Measurement temperature	Bonding temperature	D3615T
Shear strength (N/4cm ²)	23°C	100°C	471.0
		110°C	529.5
		120°C	1240.6
		130°C	1706.4
		140°C	2265.3
		150°C	2206.5
		160°C	2196.7
		170°C	2186.9
		180°C	2201.6
		190°C	2255.5
		200°C	2255.5

Adhesion failure from SUS + Cohesion failure(SUSAF+CF)

Delamination



2. Bonding strength (Push test)

<Test piece condition>

Substrate① : SUS(1.0 × 50 × 100mm)

Substrate② : PC・ABS(2.0 × 38 × 64mm)

Bonding area : 2mm × 35mm / 2 pieces

Bonding condition :

Pressure : 0.5MPa(5kgf/cm²)

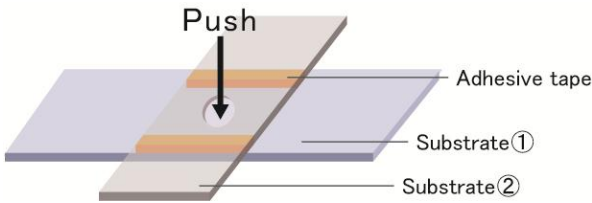
Temperature : 100 to 150°C

Set time : 3 sec

Measuring condition : 23°C±5°C 60%±20% RH

Push speed : 10mm/min

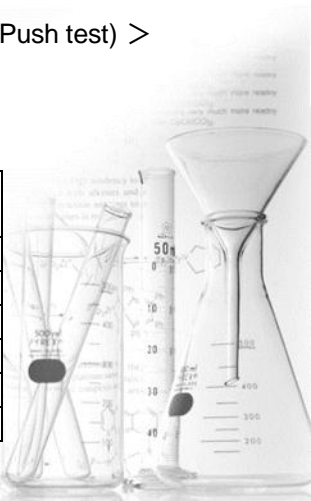
[Left at RT for one day before measurement]



<Bonding strength (Push test) >

<Results>

	Measurement temperature	Bonding temperature	D3615T (N/1.4cm ²)
Push out test (N/1.4cm ²)	23°C	100°C	367.9
		110°C	>500
		120°C	>500
		130°C	>500
		140°C	>500
		150°C	>500



3. Impact force resistance (Drop test)

<Test piece condition>

Substrate① : SUS(1.0 × 50 × 100mm)

Substrate② : PC・ABS(2.0 × 50 × 100mm)

Bonding area : 10mm × 10mm

Bonding condition :

Pressure : 0.5MPa(5kgf/cm²)

Temperature : 100 to 150°C

Set time : 3 sec

Measuring condition : 23°C±5°C 60%±20% RH

Height : 1.5m

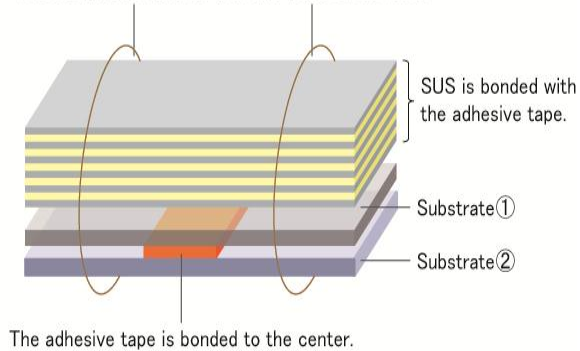
Weight : 300g

The test piece is dropped to concrete.

Record the numbers when the test piece peel off.

[Left at RT for one day before measurement]

The test piece is bundled with two-place rubber band.

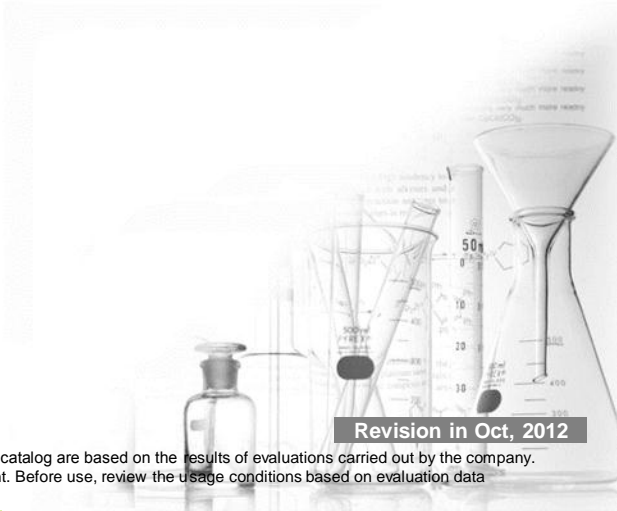


↓
The test piece is dropped from the height of 1.5m to concrete.

<Impact force resistance (Drop test) >

<Results>

	Measurement temperature	Bonding temperature	D3615T
Shock absorption test Height:1.5m Weight:300g Bonding area:1cm ² ※Record the numbers when the test piece peel off.	23°C	100°C	28
		110°C	46
		120°C	>50
		130°C	>50
		140°C	>50
		150°C	>50



Revision in Oct, 2012

◆ Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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